

**Amendments to the Specification:**

Please replace the paragraph beginning at Column 4, line 13 and ending on line 24, of the issued Patent/Application, with the following paragraph:

Referring to FIG. 6, the molded plastic casing 160 is then formed over lead frame 110, die 120 and wires 130 using known plastic molding methods (such as transfer molding) while the lead frame 110 and die 120 remain mounted on the adhesive tape 170. During the molding process, liquefied molding material flows onto exposed portions of the adhesive tape 170 which are located between the die 120 and the free ends 116 of the lead frame, and between the leads 115. This molding material solidifies to form intervening portions 162 which serve to maintain the relative positions of the die 120 and leads 115. After encapsulation, skirt ~~118~~ 119 is removed by trimming.